

N_E115DHHN-T9

(ALL PLATINGS ARE LEAD FREE AND HAVE 50μ" NICKEL UNDERPLATE)

W = GOLD FLASH

B = .000010" GOLD

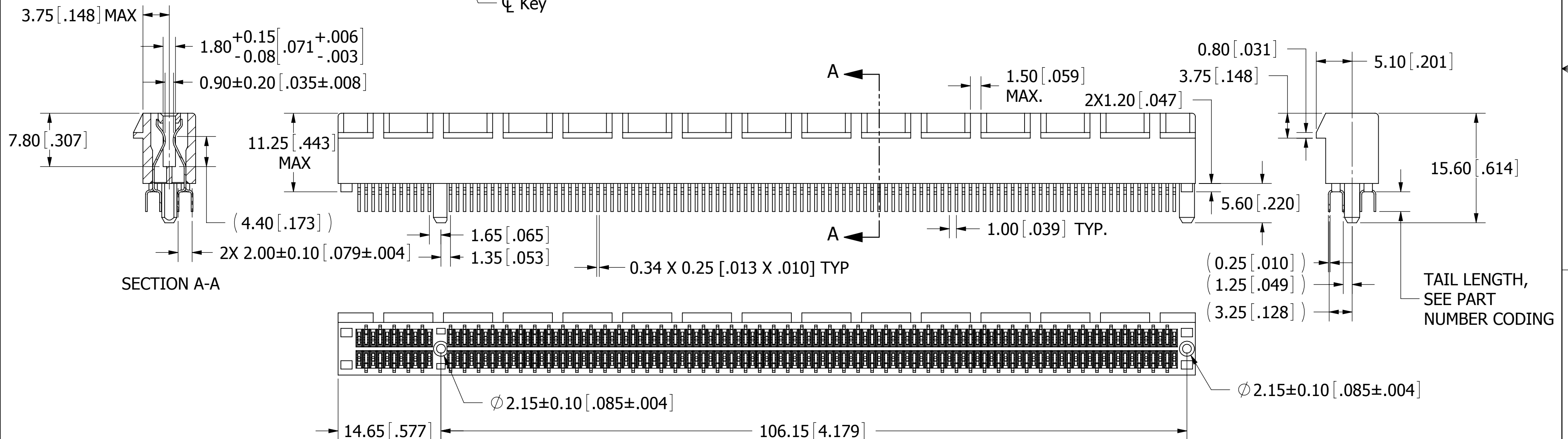
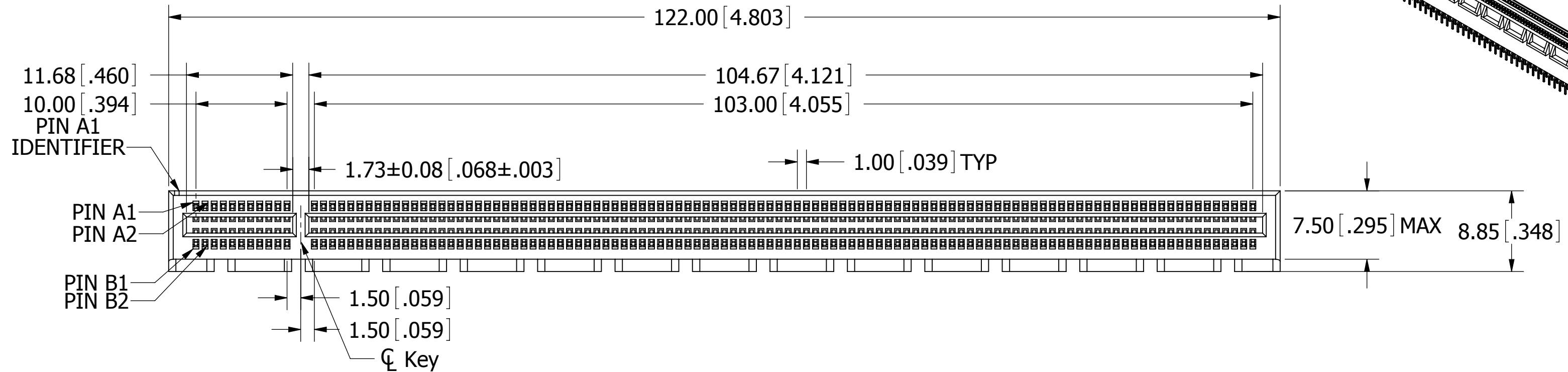
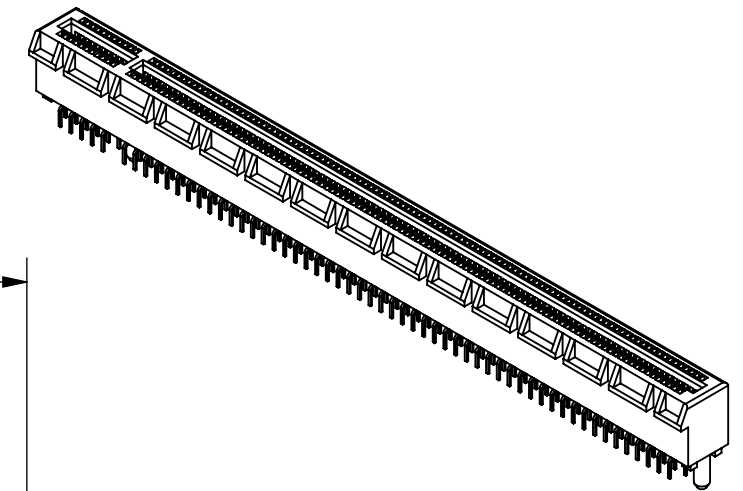
C = .000030" GOLD

$$1 = 2.30[.091]$$
$$2 = 2.54[.100]$$
$$3 = 3.10[.122]$$

1= BLACK

6= WHITE

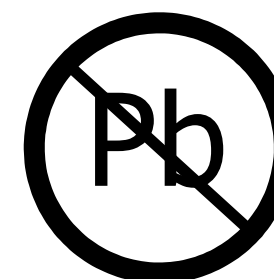
REV.	ECO. NO	DESCRIPTION	DATE	BY
A	1595	INITIAL RELEASE	04/01/08	VJ
B	1707	UPDATE P/N CODING CHART, PLATING	05/30/08	ASK
C	1912	UPDATE DRAWING VIEWS, NOTES & DIM.	02/20/09	JH
D	1946	UPDATE P/N CODING,NOTES, TOLERANCE BLOCK, DAUGHTER CARD LAYOUT	07/09/09	JH



NOTES:

1. INSULATOR MATERIAL: NYLON46, UL 94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE.
3. CONTACT PLATING: SEE PART NUMBER CODING.
4. CURRENT RATING: 1.1 AMP.
5. VOLTAGE RATING: 50 V DC.
6. INSULATOR RESISTANCE: 1000 MEGOHMS MIN.
7. CONTACT RESISTANCE: 30 MILLI OHMS MAX.
8. DIELECTRIC WITHSTANDING: 500V DC.
9. INSERTION FORCE: 117gf (1.15 N) MAX PER CONTACT PAIR USING A 1.7 mm (.067") STEEL CARD.
10. WITHDRAWAL FORCE: 15.3gf (0.15 N) MIN PER CONTACT PAIR USING A 1.44 mm (.057") STEEL CARD.
11. OPERATING TEMPERATURE: -55° C TO +105° C.
12. PROCESSING TEMP.: 260° C FOR 10 SECS MAX.

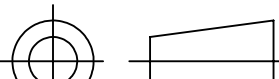
(INDICATED TEMPERATURE AND TIME IS FOR COMPONENT INSULATOR. HIGHER PROCESSING TEMPERATURE MAY BE USED, PROVIDED HEAT IS APPLIED FROM BACK SIDE OF PCB, AND INSULATOR DOES NOT EXCEED INDICATED TEMPERATURE AND TIME.)

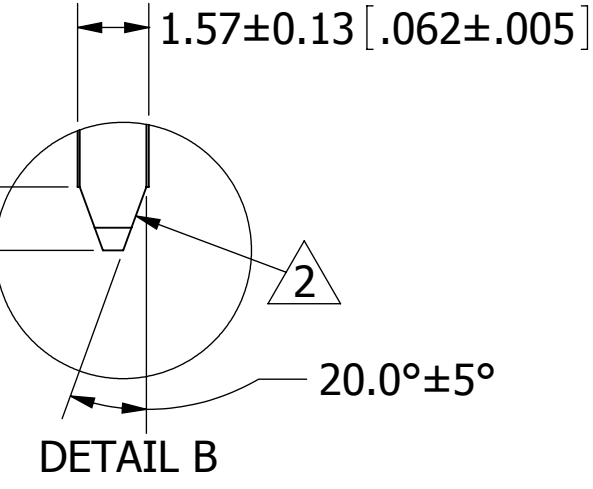
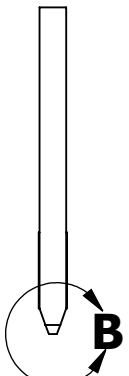
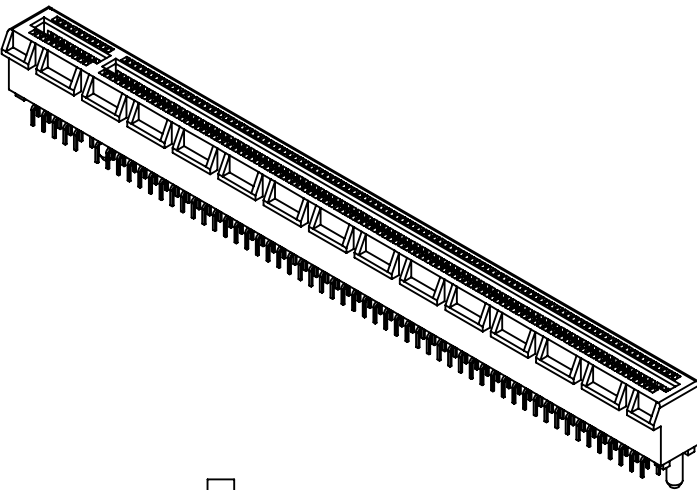
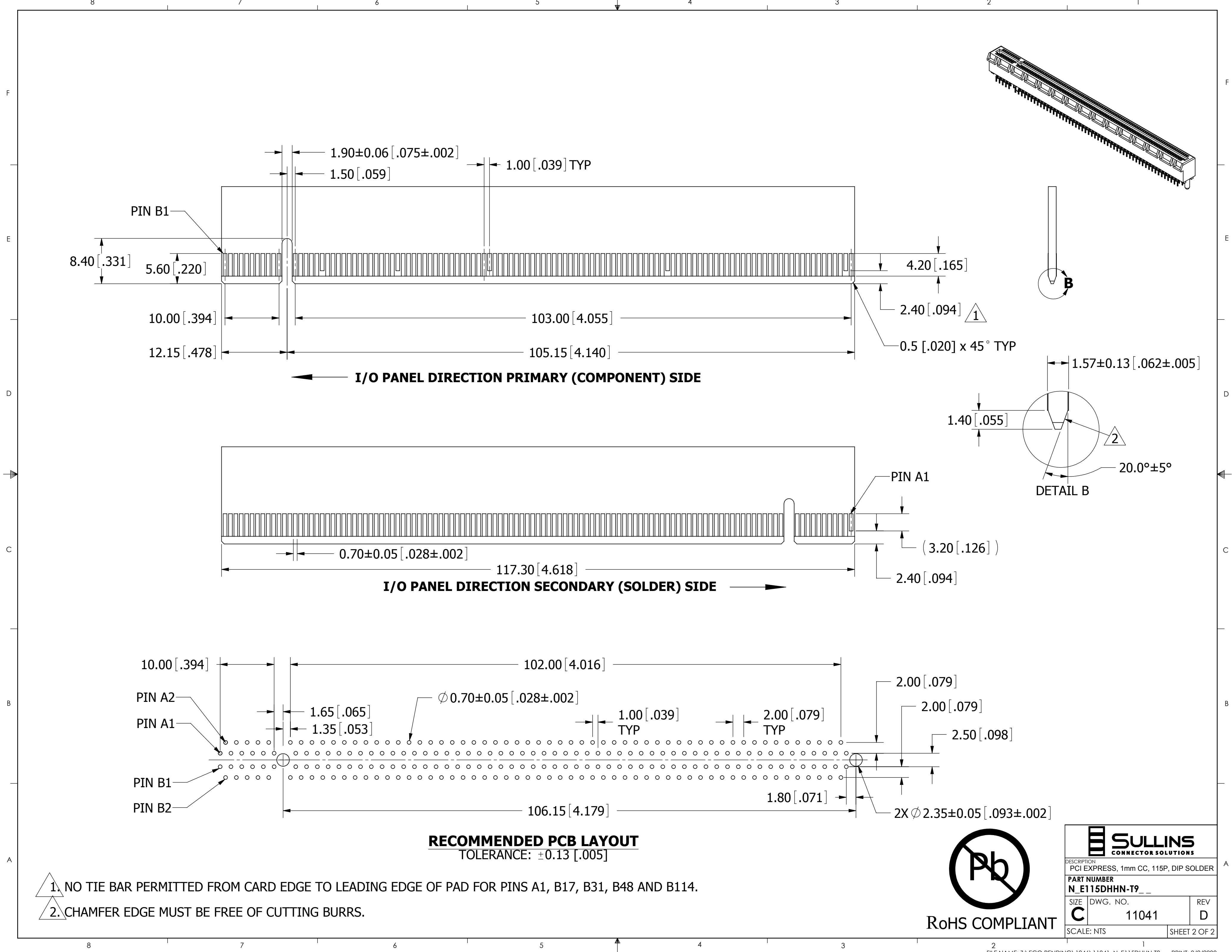


RoHS COMPLIANT

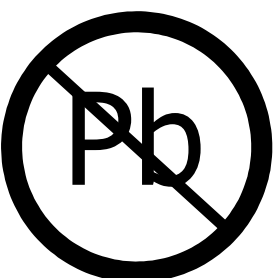
UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MM[INCHES]
TOLERANCES:
ANGULAR: $\pm 5^\circ$
.X= $\pm .3$ [.01]
.XX= $\pm .25$ [.010]
.XXX= $\pm .080$ [.0030]
SURFACE FINISH: 63 Ra
REMOVE ALL BURRS AND SHARP EDGES .010 MAX

INTERPRET DIMENSIONS AND GEOMETRIC
TOLERANCING
PER: ANSI Y14.5M-1994

	DATE	NAME	 SULLINS CONNECTOR SOLUTIONS		
DRAWN	2/24/09	JH			
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			SIZE C	DWG. NO. 11041	REV D
SCALE: 2:1					SHEET 1 OF 2



RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.13 [.005]



RoHS COMPLIANT

DESCRIPTION PCI EXPRESS, 1mm CC, 115P, DIP SOLDER		
PART NUMBER N_E115DHNN-T9__		
SIZE C	DWG. NO. 11041	REV D
SCALE: NTS		SHEET 2 OF 2

1. NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1, B17, B31, B48 AND B114.
2. CHAMFER EDGE MUST BE FREE OF CUTTING BURRS.